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REVISION HISTORY

Rev. A

INITIAL RELEASE

BOARD CHARACTERISTICS

Copper Layer Count: 6

Board Thickness: 1.6000 mm

Board overall dimensions: 102.3000 mm x 60.0000 mm

Min track/spacing: 0.0900 mm / 0.0900 mm

Min hole diameter: 0.2500 mm

Copper Finish: ENIG

Impedance Control: No

Castellated pads: No

Plated Board Edge: No

Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
F.Cu (Signal)	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In1.Cu (Ground)	copper		0.0152 mm		1	0
Dielectric	core	Copper	0.5548 mm	#D2960FFF	4.5	0.02
In2.Cu (Signal)	copper		0.0152 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In3.Cu (Ground)	copper		0.035 mm		1	0
Dielectric	core	FR4	0.5548 mm	Not specified	4.5	0.02
In4.Cu (Power)	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
B.Cu (Ground)	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

NOTES: UNLESS OTHERWISE SPECIFIED

1: MANUFACTURE TO IPC CLASS 2

TITLE1590N1 BASEBOARD – PCBA

DRAWN BYAIR

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DOCUMENT STATUSRELEASED

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APPROVED BYAIR

REVISIONA

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SHEET1/1

11x17"